

F9Z34NS-VB Datasheet

P-Channel 60 V (D-S) MOSFET

PRODUCT	PRODUCT SUMMARY			
V _{DS} (V)	$R_{DS(on)}$ (Ω) Max.	I _D (A)	Q _g (Typ.)	
- 60	0.048at V _{GS} = - 10 V	- 35	60	
- 00	0.060at V _{GS} = - 4.5 V	- 30	00	

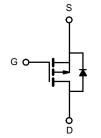
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC









P-Channel MOSFET

APPLICATIONS

- Power Switch
- Load Switch in High Current Applications
- DC/DC Converters

ABSOLUTE MAXIMUM RATINGS	$T_C = 25 ^{\circ}C$, unless other	erwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 60	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	1_	- 35	Δ.	
	T _C = 70 °C	l _D	- 30		
Pulsed Drain Current (t = 300 µs)		I _{DM}	- 100	А	
Avalanche Current		I _{AS}	- 32		
Single Avalanche Energy ^a L = 0.1 mH		E _{AS}	51	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	В	61 ^b	10/	
	T _A = 25 °C ^c	– P _D	6.1	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	°C/W	
Junction-to-Case (Drain)	R _{thJC}	3		

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 60			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 2.5	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA
Zero Gate Voltage Drain Current		V _{DS} = - 60 V, V _{GS} = 0 V			- 1	
	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 150 °C			- 250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α
	В	V _{GS} = - 10 V, I _D = - 14 A		0.048		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 12 A		0.060		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 20 V, I _D = - 14 A		40		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 30 V, f = 1 MHz		1650		pF
Output Capacitance	C _{oss}			200		
Reverse Transfer Capacitance	C _{rss}			120		
Total Gate Charge ^c	Q_g			67		nC
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30V$, $V_{GS} = -10 V$, $I_{D} = -14 A$		13.5		
Gate-Drain Charge ^c	Q_{gd}			14		
Gate Resistance	R _g	f = 1 MHz	0.5	2.5	5	Ω
Turn-On Delay Time ^c	t _{d(on)}			10	20	
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 2 Ω $I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		11	20	ns
Turn-Off Delay Time ^c	t _{d(off)}			42	63	
Fall Time ^c	t _f			12	20	
Drain-Source Body Diode Ratings ar	nd Characteri	stics T _C = 25 °C ^b				
Continuous Current	Is				- 35	А
Pulsed Current	I _{SM}				- 100	
Forward Voltage ^a	V _{SD}	I _F = - 10 A, V _{GS} = 0 V		- 0.8	- 1.5	V
Reverse Recovery Time	t _{rr}	I _F = - 10 A, dI/dt = 100 A/μs		38	57	ns
Peak Reverse Recovery Current	I _{RM(REC)}			2.3	3.5	Α
Reverse Recovery Charge	Q _{rr}	1		40	60	nC

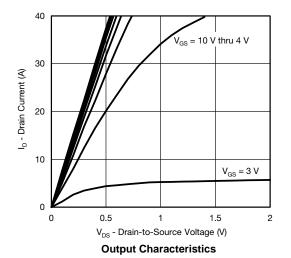
Notes:

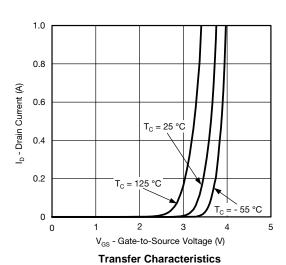
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$ b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

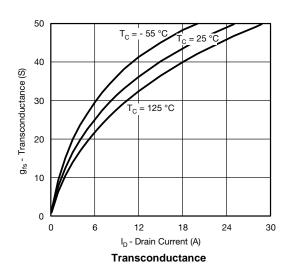
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

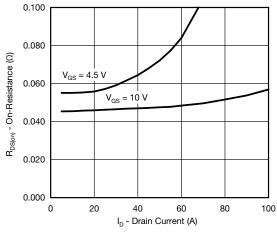


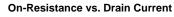
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

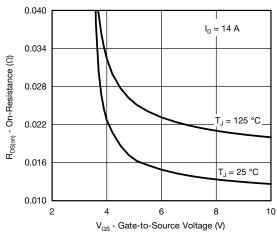




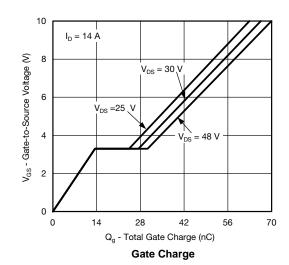






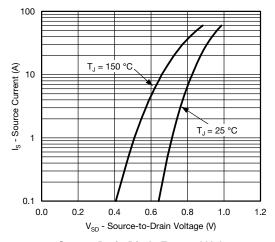


On-Resistance vs. Gate-to-Source Voltage

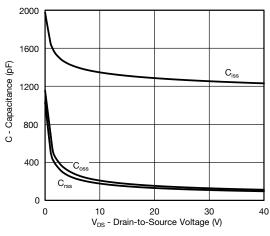




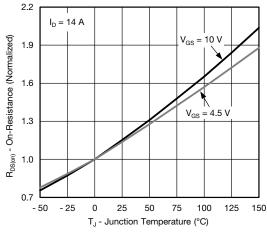
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



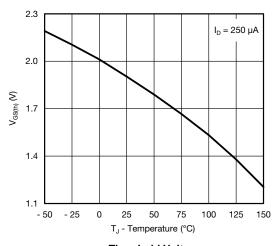
Source-Drain Diode Forward Voltage



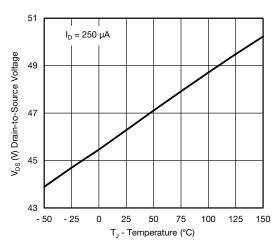
Capacitance



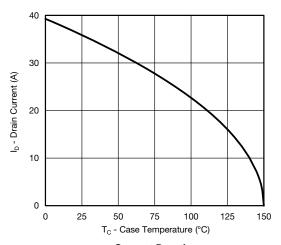
On-Resistance vs. Junction Temperature



Threshold Voltage



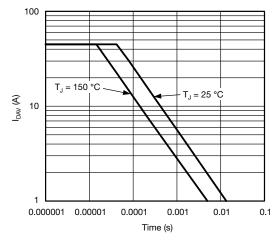
Drain Source Breakdown vs. Junction Temperature

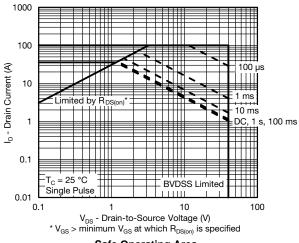


Current Derating



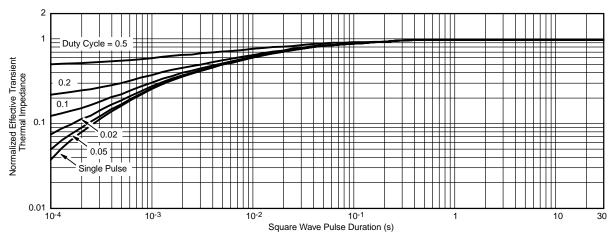
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time





Normalized Thermal Transient Impedance, Junction-to-Case

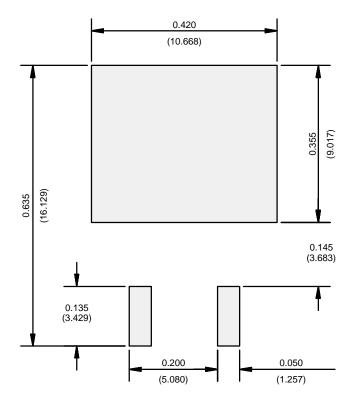
服务热线:400-655-8788

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RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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